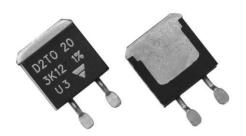
# Vishay Sfernice



# **Surface Mounted Power Resistor Thick Film Technology**

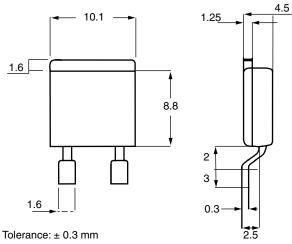


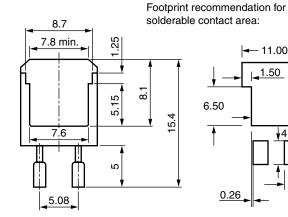
### **FEATURES**

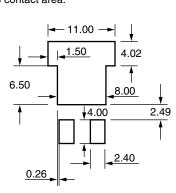
- 20 W at 25 °C case temperature
- Surface mounted resistor TO-263 (D2PAK) style
- Wide resistance range from 0.01  $\Omega$  to 550 k $\Omega$
- Non Inductive
- RoHS compliant
- · Resistor isolated from metal tab
- Solder reflow secure at 270 °C/10 s



## **DIMENSIONS** in millimeters







## **Notes**

- For the asssembly on board, we recommend the lead (Pb)-free thermal profile as per J-STD-020C
- Power dissipation is 2.8 W at an ambient temperature of 25 °C when mounted on a double sided copper board using FR4 standard, 70 µm of copper, 39 x 30 x 1.6 mm.

ELECTRICAL SPECIFICATIONS			
Resistance Range	0.01 Ω to 550 kΩ		
Tolerances (Standard)	± 1 % to 10 %		
Power Rating and Thermal Resistance	20 W at 25 °C (case temperature) R <sub>TH (j - c)</sub> : 6.5 °C/W		
Temperature Coefficient	See Special Features table Standard: ± 150 ppm/°C		
Limiting Element Voltage U <sub>L</sub>	250 V		
Dielectric Strength IEC 60115-1	2000 V <sub>rms</sub> - 1 min - 10 mA max. (between terminals and board)		
Insulation Resistance	$\geq 10^6  \text{M}\Omega$		
Inductance	≤ 0.1 µH		
Critical Resistance	3.12 ΚΩ		

SPECIAL FEATURES				
Resistance Values	≥ 0.010	≥ 0.045	≥ 0.1	≥ 0.5
Tolerances	± 1 % at ± 10 %			
Requirement Temperature Coefficient (TCR) (- 55 °C + 150 °C) IEC 60115-1	± 1100 ppm/°C ± 700 ppm/°C ± 250 ppm/°C ± 150 ppm		± 150 ppm/°C	



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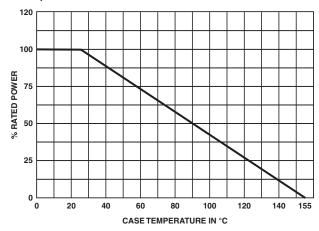
MECHANICAL SPECIFICATIONS			
Mechanical Protection Molded			
Resistive Element	Thick film		
Substrate	Alumina		
Connections	Tinned copper		
Weight	2.2 g max.		

<b>ENVIRONMENTAL SPECIFICATIONS</b>			
Temperature Range - 55 °C to 155 °C			
	IEC 60695-11-5		
Flammability	2 applications 30 s separated by 60 s		

DIMENSIONS	
Standard package	TO-263 Style (D <sup>2</sup> PAK)

## **POWER RATING**

The temperature of the case should be maintained within the limits specified.



PERFORMANCE				
TESTS	CONDITIONS	REQUIREMENTS		
Momentary Overload	IEC 60115-1 §4.13 2 Pr 5 s for $R < 2 \Omega$ 1.6 Pr 5 s for $R \ge 2 \Omega$ Us < 1.5 $U$ L	± (0.25 % + 0.005 Ω)		
Rapid Temperature Change	IEC 60115-1 Test Na 5 cycles - 1 h - 55 °C to + 155 °C	± (0.5 % + 0.005 Ω)		
Load Life	IEC 60115-1 1000 h at + 25 °C	± (1 % + 0.005 Ω)		
Humidity (Steady State)	IEC 60115-1 IEC60068-2-3 Test Ca: 56 days R.H. 95 %	± (0.5 % + 0.005 Ω)		
Vibration	MIL STD 202 Method 204 - Test. D 10 to 2000 Hz	± (0.2 % + 0.005 Ω)		
Terminal Strength	Test Ua1/Tensile: 20 N/10 s ± (0.2 % + 0.0			
Shock	IEC 60115-1 IEC 60068-2-27 Saw-tooth: 100 gn/6 ms	± (0.5 % + 0.005 Ω)		

ASSEMBLY SPECIFICATIONS  For the assembly on board, we recommend the lead (Pb)-free thermal profile as per J-STD-020C			
Resistance to Soldering Heat	IEC 60115-1 IEC 60068-2-58 Solder Bath method: 270 °C/10 s	± (0.5 % + 0.005 Ω)	
Moisture Sensitivity Level (MSL)	IPC/JEDEC J-STD-020C 85 °C/85 % RH/168 h	Level: 1 + Pass requirements of TCR Overload and Dielectic Strength after MSL	

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## Surface Mounted Power Resistor Thick Film Technology



#### CHOISE OF THE BOARD

The user must choose the board according to the working conditions of the component (power, room temperature). Maximum working temperature must not exeed 155 °C. The dissipated power is simply calculated by the following ratio:

$$P = \frac{\Delta T}{[R_{TH (j-c)}] + [R_{TH (c-a)}]}$$

P: Expressed in W

ΔΤ: Difference between maximum working temperature and room temperature

Thermal resistance value measured between resistive layer and outer side of the resistor. It is the thermal R<sub>TH (i - c)</sub>:

resistance of the component: 6.5 °C/W.

Thermal resistance value measured between outer side of the resistor and room temperature. It is the thermal  $R_{TH(c-a)}$ :

resistance of the solder layer (according the quality of the soldering) and the thermal resistance of the board.

Example:

 $R_{TH (c-a)}$  for D2TO20 power rating 2.5 W at ambient temperature + 25 °C.

Thermal resistance R<sub>TH (j - c)</sub>: 6.5 °C/W

Considering equation (1) we have:

$$\Delta T = 155 \,^{\circ}\text{C} - 25 \,^{\circ}\text{C} = 130 \,^{\circ}\text{C}$$

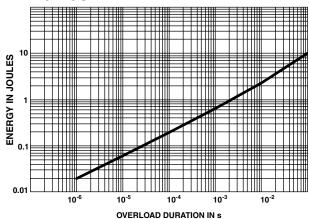
$$R_{TH (j-c)} + R_{TH (c-a)} = \Delta T/P = 130/2.5 = 52 \text{ °C/W}$$

$$R_{TH (c-a)} = 52 \text{ °C/W} - 6.5 \text{ °C/W} = 45.5 \text{ °C/W}$$

### **ACCIDENTAL OVERLOAD**

In any case the applied voltage must be lower than the maximum overload voltage of 375 V. The values indicated on the graph below are applicable to resistors in air or mounted onto a board.

#### **ENERGY CURVE**



#### Single Pulse:

These informations are for a single pulse on a cold resistor at 25 °C (not already used for a dissipation) and for pulses of 100 ms maximum duration.

The formula used to calculate E is:

$$E = P \times t = \frac{U^2}{R} \times t$$

with:

E(J): Pulse energy P(W): Pulse power t (s): Pulse duration U(V): Pulse voltage  $R(\Omega)$ : Resistor

The energy calculated must be less than that allowed by the graph.



## Surface Mounted Power Resistor Thick Film Technology

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### Repetitive or Superimposed Pulses:

The following formula is used to calculate the "equivalent" energy of a repetitive pulse or the "equivalent energy" of a pulse on a resistor that is already dissipating power.

$$E_{c} = E \times \left(1 + \frac{P_{a}}{P_{r}}\right)$$

with:

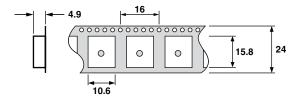
 $E_{c}$  (J): Equivalent pulse energy E (J): Known pulse energy  $P_{r}$ : Resistor power rating

Pa: Mean power being dissipated

The energy calculated must be less than that allowed by the graph and the average power dissipated  $(P_a)$  must not exceed the continuous power of resistor.

#### **PACKAGING**

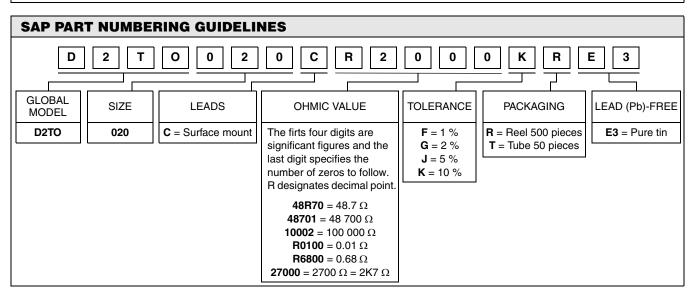
- Reel
- Tube
- Tape dimensions (mm) for reel:



#### **MARKING**

Model, Style, Resistance Value (in  $\Omega$ ), Tolerance (in %), Manufacturing Date, Vishay Trademark

ORDERING INFORMATION						
D2TO	020	С	100 k $\Omega$	± 1 %	XXX	e3
MODEL	STYLE	CONNECTIONS	RESISTANCE VALUE	TOLERANCE	CUSTOM DESIGN	LEAD (Pb)-FREE
				$F = \pm 1 \%$ $G = \pm 2 \%$ $J = \pm 5 \%$ $K = \pm 10 \%$	Optional on request: shape, etc	





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